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FXLS8965AF(Active)

Package  **VSON10** VSON10, plastic, very thin small outline package, no leads; 10 terminals; 0.4 mm pitch; 2 mm x 2 mm x 0.95 mm body



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Buy Options

FXLS8965AFR1
935377044115
Active
REEL-Reel 7" Q1/T1

Min. Package Quantity: 1000

▸
Available Distributors: FXLS8965AFR1


Operating Characteristics

No information available

Environmental Information

Material Declaration	PbFree	EU RoHS	Halogen Free	RHF Indicator	REACH SVHC	Weight (mg)
FXLS8965AFR1(935377044115)	Yes	Yes	Yes	D	REACH SVHC	14.3

Quality Information

Material Declaration	Safe Assure Functional Safety	Moisture Sensitivity Level (MSL)	Peak Package Body Temperature (PPT) (C °)	Maximum Time at Peak Temperatures (s)
		Lead Free Soldering	Lead Free Soldering	Lead Free Soldering
FXLS8965AFR1 (935377044115)	No	1	260	40

Shipping Information

Part Number	Harmonized Tariff (US) Disclaimer
FXLS8965AFR1 (935377044115)	854239

Product Change Notification

Part Number / 12NC	Issue Date	Effective Date	PCN	Title
FXLS8965AFR1 (935377044115)	2020-03-29	-	201912021AW	ASIC Die Thickness Increase for FXLS8962AFR1 and FXLS8965AFR1 Products
FXLS8965AFR1 (935377044115)	2020-03-04	2020-03-05	202002045I	Addition of SPEA DOT800 Probe in NXP Manufacturing Site in Bangkok Thailand for FXLS8962AF and FXLS8965AF
FXLS8965AFR1 (935377044115)	2020-02-27	2020-02-28	202002015I	Removal of the Cold (-40C) Test Insertion for FXLS8962AFR1 and FXLS8965AFR1
FXLS8965AFR1 (935377044115)	2020-01-05	-	201912021A	ASIC Die Thickness Increase for FXLS8962AFR1 and FXLS8965AFR1 Products
FXLS8965AFR1 (935377044115)	2020-01-04	2020-01-05	201912022I	Lead Frame Modification for FXLS8962AFR1 and FXLS8965AFR1
FXLS8965AFR1 (935377044115)	2019-09-14	2019-09-15	201908043I	Removal of the Hot (105°C) Test Insertion for FXLS8962AFR1 and FXLS8965AFR1

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